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(54) Title: LIGHT-EMITTING DIODE LIGHTING SYSTEM WITH WIREBONDED HYBRIDIZED DEVICE

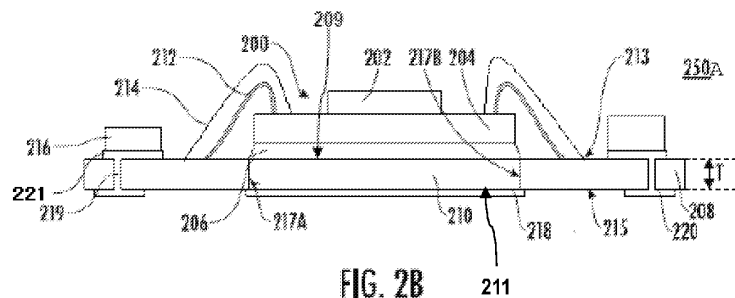


FIG. 2B

(57) Abstract: Light-emitting devices are described herein. A device includes a packaging substrate having a top surface and a bottom surface and a hybridized device having a bottom surface on the top surface of the packaging substrate. The hybridized device includes a silicon backplane that includes input/output (I/O) pins and a light-emitting diode (LED) array having a bottom surface on a top surface of the silicon backplane. Passive components are disposed on the top surface of the packaging substrate. Conductive connectors are electrically coupled between the top surface of the hybridized device and the top surface of the packaging substrate.



WO 2021/158912 A1